

Appl. No. 10/748,480

Amdt. dated July 28, 2005

Reply to Office action dated Jun. 28, 2005

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of claims:**

1-9. (canceled)

10. (currently amended) A circuit board assembly comprising:

a circuit board, ~~the circuit board~~ comprising a board pad;

a component package, ~~the component package~~ comprising a terminal [[pad,]] with a planar base area; wherein the terminal pad includes a pad feature and a pad base and wherein the pad feature is aligned with the board pad;

the terminal including a elongated member, having an outer surface and a cross section area, extending from the terminal base; and

a solder deposit having a hourglass shape, covering the board pad and the outer surface of the elongated member wherein the solder deposit is operable to flow along the pad feature when liquefied and to form a solder joint when cooled, the solder joint abutting the pad base and the board base.

11. (canceled)

12. (currently amended) The circuit board assembly of Claim 10, wherein ~~the pad feature comprises~~ the elongated member has a J-hook shape.

13. (currently amended) The circuit board assembly of Claim 10, wherein the board pad has a surface area comprises a first width, and wherein the pad feature comprises a peg, wherein the peg comprises a second width, the first width being greater than the second width. greater than the cross section area of the elongated member.

14. (currently amended) The circuit board assembly of Claim 10, wherein the ~~pad feature comprises~~ elongated member has a conic shape.

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15. (canceled)

16. (original) The circuit board assembly of Claim 10, wherein the component package comprises a Quad Flat No-lead (QFN) package.

17. (original) The circuit board assembly of Claim 10, wherein the component package comprises a Small Outline No-lead (SON) package.

18-20. (canceled)

21. (new) The circuit board assembly of claim 1, in which the solder deposit has a length that is approximately the length of the elongated member.

22. (new) The circuit board assembly of claim 21, in which the cross section of the solder deposit along its length is smaller than the planar base area of the terminal.

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